PCB MANUFACTURING INFORMATION

CONSTRUCTION

FAB SPECIFICATION	IPC-6012 CLASS	■ 2	☐ 3	☐ MIL-SPEC P-55110
LEAD-FREE RoHS	☐ YES	☐ NOT REQD		
MATERIAL	■ FR4	☐ FR408HR	☐ OTHER_____	
SPECIAL CORES	☐ YES	■ NO	☐ OTHER_____	
FINAL PCB THICKNESS	■ 1.6mm			
THICKNESS TOLERANCE	■ 10%			
LAYER COUNT	☐ 2			
LAYER STACK-UP	■ MECHANICAL LAYER		☐ FILENAME _____	
ALLOW PCB ROTATION	■ NO	☐ YES - 90 / 270 DEGREES		
IMPEDANCE CONTROL	■ NO	☐ YES	☐ PER STACKUP	
SUPPLY TEST COUPONS	■ NO	☐ YES		
BOARD EDGE	■ NO EXPOSED COPPER			
BOW & TWIST	■ 0.75% SMT (IPC-TM-650 Method 2.4.22)			
PROFILING	☐ NC-ROUTE	☐ V-SCORE	☐ BOTH AS INDICATED	
PROFILE TOLERANCE	☐ +/- 0.15mm	☐ +/- 0.2mm	■ +/-0.25mm	

CONDUCTIVE MATERIAL

QTY SIGNAL LAYERS	■ 2		
QTY COPPER PLANES	☐ 0		
MIN TRACE WIDTH	☐ 0.5mm		
MIN CLEARANCE	☐ 0,4mm		
Cu TRACE TOLERANCE	☐ +/- 5%mm	■ +/- 10%	☐ +/- 15%
Cu THICKNESS INTERNAL	☐ 17um	☐ 35um	☐ PER STACKUP
FINAL Cu THICKNESS EXT	☐ 17um	■ 35um	☐ PER STACKUP
PLATING FINISH	☐ ENIG	☐ FLASH GOLD	☐ OTHER____
EXTERNAL PLATING	☐ CLASS 2 - 20um	☐ CLASS 3 - 25um	☐
SELECTIVE Au PLATING	■ NO	☐ AS INDICATED	☐ ON EDGE FINGERS

INTERCONNECTS

DRILL PROCESS	■ THT	☐ BLIND & BURIED VIAS	☐ MICRO VIAS
FILLED VIAS	☐ NO	☐ YES	☐ SELECTIVE
IPC-4761 VIA TYPE	☐ I(a) TENTED	☐ VI - FILLED & COVERED	☐ VII - FILLED & CAPPED
FILLING METHOD	☐ CONDUCTIVE	☐ NON-CONDUCTIVE	
HOLE PLATING	■ CLASS 2 - 20um	☐ CLASS 3 - 25um	
MIN DRILL SIZE	☐ 0.25mm		
MIN FINISHED HOLE	■ 1mm		
MIN HOLE TO COPPER	☐ 0.2mm		
FINAL HOLE SIZE	■ AS PER DRILL TABLE		☐ CUSTOM INSTRUCTION
HOLE SIZE TOLERANCE	☐ +/- 0,075mm	■ +/- 0,1mm	☐ +/- 0,215mm
HOLE POSITION TOL (GDT)	☐ 0.075mm	■ 0.085mm	
MIN ASPECT RATIO	☐ 6.4: 1		

COSMETICS

SOLDERMASK SIDES	☐ TOP	☐ BOT	■ BOTH SIDES		
SOLDERMASK TYPE	■ PHOTO IMAGEABLE (SMOBC)				
SOLDERMASK COLOUR	☐ GREEN	☐ BLUE	☐ RED	☐ BLACK	☐ WHITE
SOLDERMASK WEBBING	☐ GANG RELIEF NOT ALLOWED, UNLESS BELOW CAPABILITY				
SILKSCREEN COLOUR	■ WHITE	☐ YELLOW	☐ OTHER _____		
SILKSCREEN PRINT	■ NO LEGEND TO BE APPLIED OVER SOLDER PADS				
SILKSCREEN QTY	☐ TOP	☐ BOT	■ BOTH SIDES		
SILKSCREEN OVER PADS	■ NOT PERMITTED, PLEASE REMOVE IF PRESENT				

MANUFACTURING DEVIATIONS

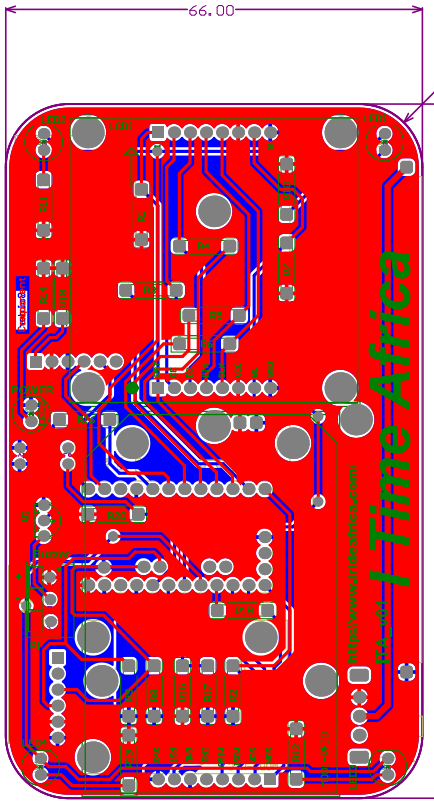
PAD REMOVAL	■ NO	☐ ALLOWED ON UNUSED PADS ON INNER LAYERS
TEARDROPPING	☐ NO	■ YES
THIEVING	☐ NO	☐ WHERE INDICATED ☐ ALLOWED ON PANEL STRIPS

ADDITIONAL REQUIREMENTS

ELECTRICAL TEST	☐ NONE		☐ FLYING PROBE	
MANUFACTURER LOGO	■ ALLOWED	☐ NO		
BATCH No ON S/SCREEN	■ YES	☐ NO		
CERTIFICATE REQ'D	☐ E-TEST	☐ UL94	☐ IPC-6011/12	☐ MIL-SPEC P-55110
SILKSCREEN SERIAL #	☐ YES	■ NO		

FINGER EDGE CONNECTOR

PLATING THICKNESS	☐ 1um	☐ 2um	☐ 5um
PLATING TYPE	☐ HARD GOLD		☐ ENIG
CHAMPHER ANGLES	☐ 20°	☐ 30°	☐ 45°
CHAMPHER HEIGHT	☐ ???		
DETAIL	☐ NO	☐ YES, SEE MECHANICAL LAYER	



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	1.500mm	4.2	
5	Bottom Layer	Copper	0.036mm		
6	Solder Side	Solder Resist	0.010mm	3.5	
7	Bottom Overlay				

PCB ASSEMBLY INSTRUCTIONS		
1: RoHS BUILD	☐ NO	■ YES
2: WASH PCB	■ NO	☐ YES
3: THL COMPONENT LEGS	■ < 2mm CUT BEFORE ASSEMBLY	
4: BREAK PCB FROM PANEL	■ NO	☐ YES
5: X-RAY PCB	■ NO	☐ YES
6: OPTICAL INSPECTION	☐ NO	■ YES
7: BASIC ELECTRICAL TEST	■ NO	☐ YES
8: ASSEMBLY CALIBRATION	■ NO	☐ YES
9: PRODUCTION PROGRAMMING	■ NO	☐ YES
10: CONFORMAL COATING	■ NO	☐ YES
11: STATIC SENSITIVE	☐ NO	■ YES

Assembly Variant: [No Variations]

.ASY_Rev_5	.ASY_Drawn_5	.ASY_Date_5	.ASY_Engineer_5	.ASY_ECO_5	PCB FILENAME:	ASSEMBLY DRAWING		
.ASY_Rev_4	.ASY_Drawn_4	.ASY_Date_4	.ASY_Engineer_4	.ASY_ECO_4	ITA_v01.PcbDoc	Time Africa		
.ASY_Rev_3	.ASY_Drawn_3	.ASY_Date_3	.ASY_Engineer_3	.ASY_ECO_3		I Ride Africa	.PRJ_Title	
.ASY_Rev_2	.ASY_Drawn_2	.ASY_Date_2	.ASY_Engineer_2	.ASY_ECO_2			ITA_v01	
.ASY_Rev_1	.ASY_Drawn_1	.ASY_Date_1	.ASY_Engineer_1	.ASY_ECO_1			.PRJ_Number_ASSY	SHEET 1 OF 2